

AW-CM358MA

**IEEE 802.11a/b/g/n/ac WLAN with
Bluetooth 5.2 Combo Stamp Module
With M.2 2230 Adaptor Board**

Datasheet

Rev. J

0B

(For Standard)

Features

WLAN

- ◆ 1 antennas to support 1(Transmit) × 1(Receive) technology and Bluetooth
- ◆ High speed wireless connection up to 433.3Mbps transmit/receive PHY rate using 80MHz bandwidth
- ◆ Backward compatibility with legacy 802.11n/a/g/b technology.
- ◆ 20MHz bandwidth/ channel, 40MHz bandwidth/ channel, upper/ lower 20MHz packets in 40MHz channel, 20MHz duplicate legacy packets in 40MHz channel mode operation.
- ◆ 80MHz bandwidth/ channel, 4 positions of 20MHz packets in 80MHz channel, upper/ lower 40MHz packets in 80MHz channel, 20MHz quadruplicate legacy packets in 80MHz channel mode operation.
- ◆ Dynamic frequency selection (radar detection)

Bluetooth

- ◆ Baseband and radio BDR and EDR packet types – 1Mbps (GFSK), 2Mbps ($\pi/4$ -DQPSK), and 3Mbps (8DPSK).
- ◆ Bluetooth 5.2 support.
- ◆ Enhanced Data Rate (EDR) compliant for both 2Mbps and 3Mbps supported.
- ◆ High speed UART and PCM for Bluetooth.
- ◆ Fully functional Bluetooth baseband-AFH, forward error correction, header error control, access code correlation, CRC, encryption bit stream generation, and whitening.

- ◆ Enhanced radar detection for long and short pulse radar.
- ◆ Enhanced AGC scheme for DFS channel.
- ◆ 20/40/80Mhz coexistence with middle-packet detection (GI detection) for enhanced CCA.
- ◆ 1 spatial stream STBC reception.
- ◆ LDPC transmission and reception for both 802.11n and 802.11ac.
- ◆ 256 QAM (MCS 8, 9) modulation, optional support for 802.11ac MCS 9 in 20MHz using LDPC.
- ◆ Short guard interval.
- ◆ Temporal Key Integrity Protocol (TKIP)/ Wired Equivalent Privacy (WEP)/ Advanced Encryption Standard (AES)/ Counter-Mode/ CBC-MAC Protocol (CCMP).
- ◆ Cipher-Based Message Authentication Code (CMAC)/ WLAN Authentication and Privacy Infrastructure (WAPI).
- ◆ External Crystal frequency
- ◆ Adaptive Frequency Hopping (AFH) using Packet Error Rate (PER).
- ◆ SCO/ eSCO links with hardware accelerated audio signal processing and hardware supported PPEC algorithm for speech quality improvement.
- ◆ Standard Bluetooth power saving mechanisms.
- ◆ Automatic ACL packet type selection.
- ◆ Full master and slave piconet support.
- ◆ Scatternet support.
- ◆ Enhanced Power Control (EPC).



- ◆ Channel Quality Driven Data Rate (CQDDR).
- ◆ Encryption (AES) support.
- ◆ Supports link layer topology to be master and slave (connects up to 16 links).
- ◆ LE Privacy 1.2
- ◆ LE Secure Connection.
- ◆ LE Data Length Extension.
- ◆ 2 Mbps LE

Revision History

Document NO: R2-2358MA-DST-02

Version	Revision Date	DCN NO.	Description	Initials	Approved
A	2019/09/03	DCN016213	● Initial Version	JM.Pang	Chihhao Liao
B	2020/10/22	DCN019076	● 2.2 Pin table update	JM.Pang	Chihhao Liao
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D	2021/04/17	DCN021501	● Datasheet format update	JM.Pang	Chihhao Liao
E	2021/08/05	DCN022881	● Update to BT5.2	JM.Pang	Chihhao Liao
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Table of Contents

Features	2
Revision History	4
Table of Contents	5
1. Introduction.....	6
1.1 Product Overview	6
1.2 Block Diagram.....	7
1.3 Specifications Table	8
1.3.1 General	8
1.3.2 WLAN	8
1.3.3 Bluetooth.....	10
1.3.4 Operating Conditions.....	11
2. Pin Definition	12
2.1 Pin Map.....	12
2.2 Pin Table.....	13
3. Electrical Characteristics	16
3.1 Absolute Maximum Ratings	16
3.2 Recommended Operating Conditions	16
3.3 Digital IO Pin DC Characteristics	16
3.4 Power up Timing Sequence	17
3.4.1 SDIO Host Interface Specification	18
3.4.2 UART Interface	24
3.4.3 Frequency Reference.....	26
3.5 Power Consumption*	27
3.5.1 WLAN	27
3.5.2 Bluetooth.....	27
4. Mechanical Information	28
4.1 Mechanical Drawing	28
5. Packaging Information	29

1. Introduction

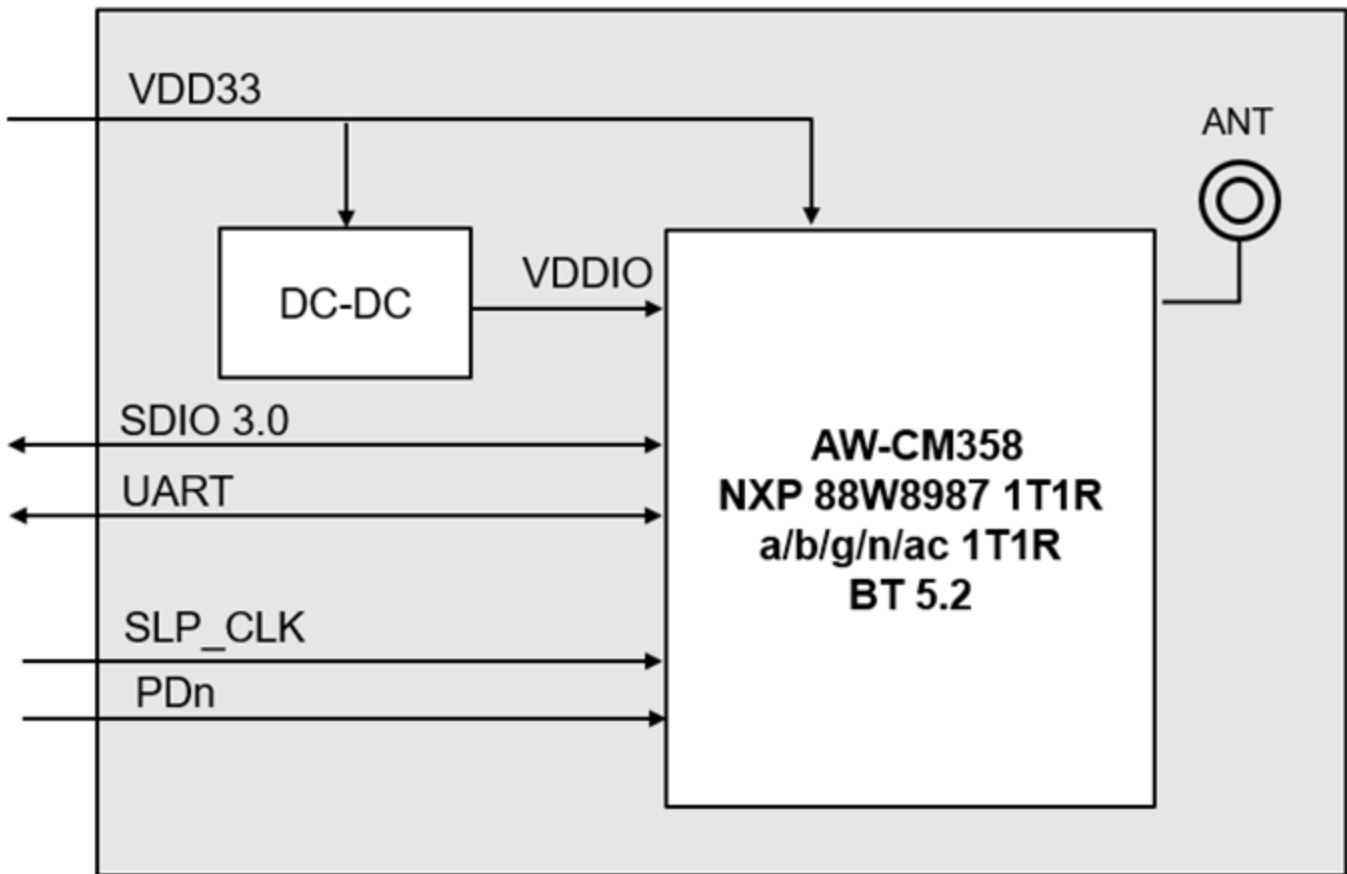
1.1 Product Overview

AzureWave Technologies, Inc. introduces the pioneer of the IEEE 802.11 a/b/g/n/ac WIFI with Bluetooth 5.2 combo SDIO and UART Stamp Module --- **AW-CM358MA**. The AW-CM358MA IEEE 802.11 a/b/g/n/ac WIFI with Bluetooth 5.2 combo module is a highly integrated wireless local area network (WLAN) solution to let users enjoy the digital content through the latest wireless technology without using the extra cables and cords. It combines with Bluetooth 4.2 and provides a complete 2.4GHz Bluetooth system which is fully compliant to Bluetooth 4.2 and v2.1 that supports EDR of 2Mbps and 3Mbps for data and audio communications. It enables a high performance, cost effective, low power, compact solution that easily fits onto the SDIO and UART combo stamp module. Generic interfaces include SDIO 3.0 and high-speed UART interfaces for connecting WLAN and Bluetooth technologies to the host processor.

AW-CM358MA uses Direct Sequence Spread Spectrum (DSSS), Orthogonal Frequency Division Multiplexing (OFDM), BPSK, QPSK, CCK and QAM baseband modulation technologies. A high level of integration and full implementation of the power management functions specified in the IEEE 802.11 standard minimize the system power requirements by using AW-CM358MA. In addition to the support of **WPA/WPA2/WPA3** and **WEP** 64-bit and 128-bit encryption, It also supports the **IEEE 802.11i** security standard through the implementation of **Advanced Encryption Standard (AES)/Counter Mode CBC-MAC Protocol (CCMP)**, Wired Equivalent Privacy (**WEP**) with Temporal Key Integrity Protocol (**TKIP**), Advanced Encryption Standard (**AES**)/Cipher-Based Message Authentication Code (**CMAC**), and WLAN Authentication and Privacy Infrastructure (**WAPI**) security mechanisms. For video, voice, and multimedia applications, 802.11e Quality of Service (QoS) is supported. The device also supports 802.11h Dynamic Frequency Selection (DFS) for detecting radar pulses when operating in the 5 GHz range.

Wireless home audio and video entertainment systems including DVT, set-top boxes, blue-ray DVD players, media servers, and gaming consoles. Mobile routers and Internet of Things (IoT) gateways. AW-CM358MA module adopts NXP's latest highly-integrated WLAN & Bluetooth SoC---**88W8987**. All the other components are implemented by all means to reach the mechanical specification required.

1.2 Block Diagram



AW-CM358MA BLOCK DIAGRAM

1.3 Specifications Table

1.3.1 General

Features	Description
Product Description	IEEE 802.11a/b/g/n/ac WLAN with Bluetooth 5.2 Combo Stamp Module With M.2 2230 Adaptor Board
Major Chipset	NXP 88W8987
Host Interface	Wi-Fi: SDIO , BT: UART
Dimension	22 mm X 30mm x 2.65 mm
Package	M.2 2230 E key
Antenna	I-PEX MHF4 Connector Receptacle (20449) ANT(Main): Wi-Fi/Bluetooth → TX/RX
Weight	2.1g

1.3.2 WLAN

Features	Description
WLAN Standard	IEEE802.11 a/b/g/n/ac
WLAN VID/PID	N/A
WLAN SVID/SPID	N/A
Frequency Range	2.4 GHz ISM Bands 2.412-2.472 GHz 5.15-5.25 GHz (FCC UNII-low band) for US/Canada and Europe 5.25-5.35 GHz (FCC UNII-middle band) for US/Canada and Europe 5.47-5.725 GHz for Europe 5.725-5.825 GHz (FCC UNII-high band) for US/Canada
Modulation	802.11a/g/n/ac: OFDM 802.11b: CCK(11, 5.5Mbps), DQPSK(2Mbps), BPSK(1Mbps)
Number of Channels	802.11b: USA, Canada and Taiwan – 1 ~ 11 Most European Countries – 1 ~ 13 802.11g: USA and Canada – 1 ~ 11 Most European Countries – 1 ~ 13 802.11n: USA and Canada – 1 ~ 11 Most European Countries – 1 ~ 13 802.11a:

	USA – 36, 40, 44, 48, 52, 56, 60, 64, 100, 104, 108, 112, 116, 120, 124, 128, 132, 136, 140, 149, 153, 157, 161, 165				
Output Power (Board Level Limit)*	2.4G				
		Min	Typ	Max	Unit
	11b (11Mbps) @EVM<35%	14	16	18	dBm
	11g (54Mbps) @EVM \leq -27 dB	12	14	16	dBm
	11n (HT20 MCS7) @EVM \leq -28 dB	11	13	15	dBm
	11n (HT40 MCS7) @EVM \leq -28 dB	10	12	14	dBm
	5G				
		Min	Typ	Max	Unit
	11a (54Mbps) @EVM \leq -27 dB	11	13	15	dBm
	11n (HT20 MCS7) @EVM \leq -28 dB	8	10	12	dBm
	11n (HT40 MCS7) @EVM \leq -28 dB	8	10	12	dBm
	11ac (VHT20 MCS8) @EVM \leq -30 dB	8	10	12	dBm
	11ac (VHT40 MCS9) @EVM \leq -32 dB	7	9	11	dBm
	11ac (VHT80 MCS9) @EVM \leq -32 dB	6	8	10	dBm
	Receiver Sensitivity	2.4G			
		Min	Typ	Max	Unit
11b (11Mbps)			-87	-84	dBm
11g (54Mbps)			-73	-70	dBm
11n (HT20 MCS7)			-69	-66	dBm
11n (HT40 MCS7)			-67	-64	dBm
5G					
		Min	Typ	Max	Unit
11a (54Mbps)			-71	-68	dBm
11n (HT20 MCS7)			-67	-64	dBm
11n (HT40 MCS7)			-63	-60	dBm
11ac (VHT20 MCS8)			-67	-64	dBm
11ac (VHT40 MCS9)			-59	-56	dBm
11ac (VHT80 MCS9)			-55	-52	dBm
Data Rate		WLAN: 802.11b : 1, 2, 5.5, 11Mbps 802.11a/g : 6, 9, 12, 18, 24, 36, 48, 54Mbps			

	802.11ac/n : Maximum data rates up to 86.7 Mbps(20MHz channel),200 Mbps (40 MHz channel), 433 Mbps (80 MHz channel)
Security	<ul style="list-style-type: none"> ● WPA/WPA2 and WEP 64-bit and 128-bit encryption ● Advanced Encryption Standard (AES)/Counter Mode CBC-MAC Protocol (CCMP) ● Wired Equivalent Privacy (WEP) /Temporal Key Integrity Protocol (TKIP) ● Advanced Encryption Standard (AES)/Cipher-Based Message Authentication Code (CMAC) ● WLAN Authentication and Privacy Infrastructure (WAPI) ● WPA3

* If you have any certification questions about output power please contact FAE directly.

1.3.3 Bluetooth

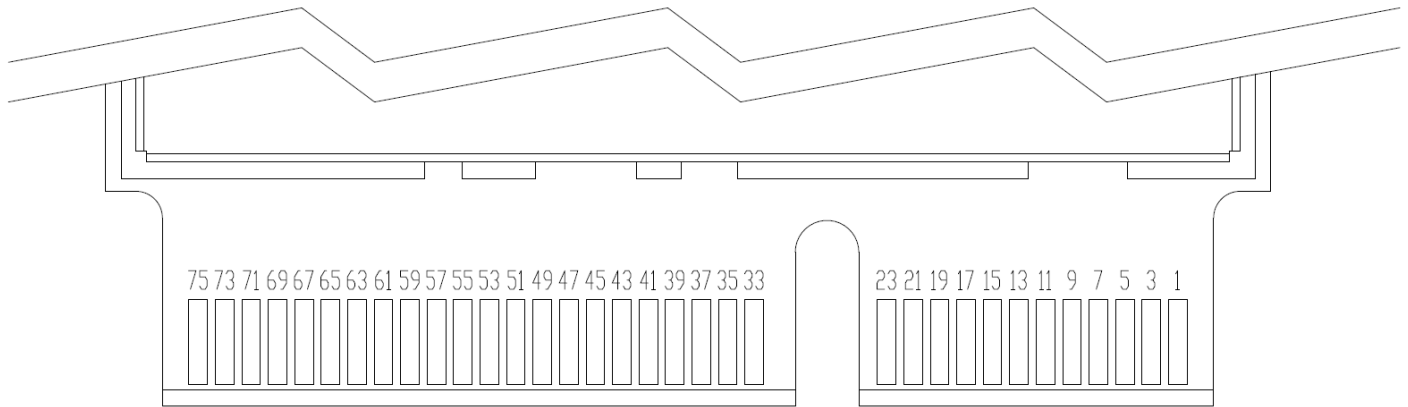
Features	Description				
Bluetooth Standard	Bluetooth 5.2				
Bluetooth VID/PID	N/A				
Frequency Range	2402MHz~2483MHz				
Modulation	Header GFSK Payload 2M: $\pi/4$ -DQPSK Payload 3M: 8DPSK				
Output Power		Min	Typ	Max	Unit
	BDR	0	2	4	dBm
	EDR	0	2	4	dBm
	Low Energy	0	2	4	dBm
Receiver Sensitivity	BT Sensitivity (BER<0.1%)				
		Min	Typ	Max	Unit
	GFSK		-88	-86	dBm
	$\pi/4$ -DQPSK		-88	-86	dBm
	8DPSK		-80	-78	dBm

1.3.4 Operating Conditions

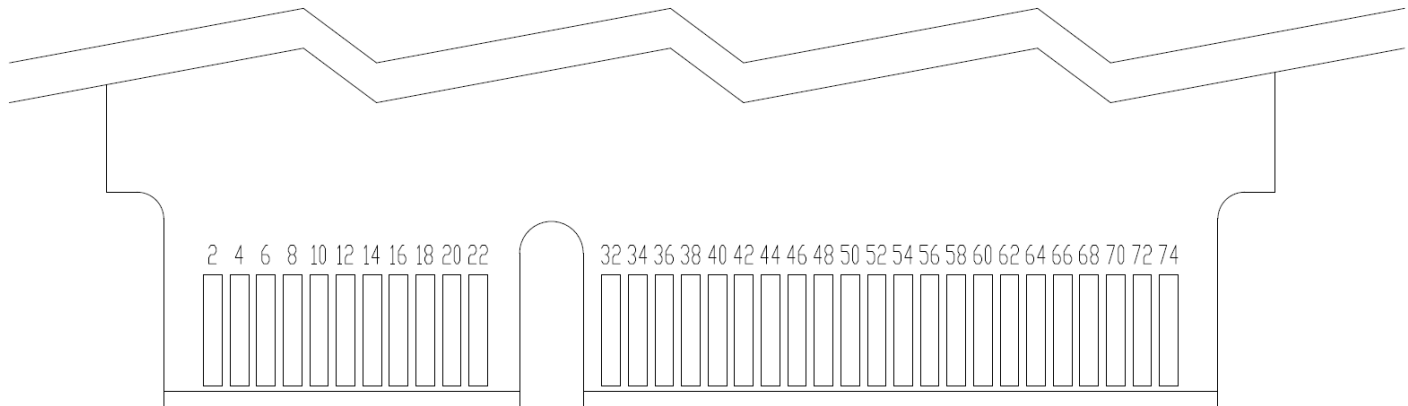
Features	Description
Operating Conditions	
Voltage	VBAT: 3.07~3.53
Operating Temperature	-30 °C to +85 °C
Operating Humidity	Less than 85%R.H.
Storage Temperature	-40 °C to +85 °C
Storage Humidity	Less than 60%R.H.

2. Pin Definition

2.1 Pin Map



AW-CM358MA Pin Map (Top View)



AW-CM358MA Pin Map (Bottom View)

2.2 Pin Table

Pin No	Definition	Basic Description	Voltage	Type
1	GND	Ground.		GND
2	VBAT	3.3V power pin	3.3V	VCC
3	NC	Floating Pin, No connect to anything.		
4	VBAT	3.3V power pin	3.3V	VCC
5	NC	Floating Pin, No connect to anything.		
6	NC	Floating Pin, No connect to anything.		
7	GND	Ground.		GND
8	BT_PCM_CLK	PCM Clock	0/1.8V	I/O
9	SDIO_CLK	SDIO Clock Input	0/1.8V	I
10	BT_PCM_SYNC	PCM Synchronization control	0/1.8V	O
11	SDIO_CMD	SDIO Command Input	0/1.8V	I/O
12	BT_PCM_OUT	PCM data out	0/1.8V	O
13	SDIO_DATA0	SDIO Data Line 0	0/1.8V	I/O
14	BT_PCM_IN	PCM data Input	0/1.8V	I
15	SDIO_DATA1	SDIO Data Line 1	0/1.8V	I/O
16	NC	Floating Pin, No connect to anything.		
17	SDIO_DATA2	SDIO Data Line 2	0/1.8V	I/O
18	GND	Ground.		GND
19	SDIO_DATA3	SDIO Data Line 3	0/1.8V	I/O
20	UART_WAKE	Bluetooth device to wake-up Host	0/3.3V	O
21	SDIO_WAKE	WLAN to wake-up HOST	0/1.8V	O
22	UART_TXD	High-Speed UART Data Out	0/1.8V	O
23	SDIO Reset	Power up/ down internal regulators. 0 = full power-down mode	0/1.8V	I

		1 = normal mode Default pull high in module internal, this pin has an internal 4.02k pull-high resistor. For external pull-low setting, suggest to use 1.6k resistor or below to pull-low.		
32	UART_RXD	High-Speed UART Data In	0/1.8V	I
33	GND	Ground.		GND
34	UART_RTS_N	High-Speed UART RTS	0/1.8V	O
35	NC	Floating Pin, No connect to anything.		
36	UART_CTS_N	High-Speed UART CTS	0/1.8V	I
37	NC	Floating Pin, No connect to anything.		
38	NC	Floating Pin, No connect to anything.		
39	GND	Ground.		GND
40	NC	Floating Pin, No connect to anything.		
41	NC	Floating Pin, No connect to anything.		
42	NC	Floating Pin, No connect to anything.		
43	NC	Floating Pin, No connect to anything.		
44	NC	Floating Pin, No connect to anything.		
45	GND	Ground.		GND
46	NC	Floating Pin, No connect to anything.		
47	NC	Floating Pin, No connect to anything.		
48	NC	Floating Pin, No connect to anything.		
49	NC	Floating Pin, No connect to anything.		
50	SUSCLK_IN	External 32K or RTC clock	0/3.3V	I
51	GND	Ground.		GND
52	NC	Floating Pin, No connect to anything.		
53	NC	Floating Pin, No connect to anything.		
54	NC	Floating Pin, No connect to anything.		

55	NC	Floating Pin, No connect to anything.		
56	W_Disable1	Power up/ down internal regulators. 0 = full power-down mode 1 = normal mode Default pull high in module internal, this pin has an internal 4.02k pull-high resistor. For external pull-low setting, suggest to use 1.6k resistor or below to pull-low.	0/3.3V	I
57	GND	Ground.		GND
58	NC	Floating Pin, No connect to anything.		
59	NC	Floating Pin, No connect to anything.		
60	NC	Floating Pin, No connect to anything.		
61	NC	Floating Pin, No connect to anything.		
62	NC	Floating Pin, No connect to anything.		
63	GND	Ground.		GND
64	NC	Floating Pin, No connect to anything.		
65	NC	Floating Pin, No connect to anything.		
66	NC	Floating Pin, No connect to anything.		
67	NC	Floating Pin, No connect to anything.		
68	NC	Floating Pin, No connect to anything.		
69	GND	Ground.		GND
70	NC	Floating Pin, No connect to anything.		
71	NC	Floating Pin, No connect to anything.		
72	VBAT	3.3V power pin	3.3V	VCC
73	NC	Floating Pin, No connect to anything.		
74	VBAT	3.3V power pin	3.3V	VCC
75	GND	Ground.		GND

3. Electrical Characteristics

3.1 Absolute Maximum Ratings

Symbol	Parameter	Minimum	Typical	Maximum	Unit
VDD33	DC supply for the 3.3V input	-0.5	3.3	4.0	V

3.2 Recommended Operating Conditions

Symbol	Parameter	Minimum	Typical	Maximum	Unit
VDD33	DC supply for the 3.3V input	3.07	3.3	3.53	V

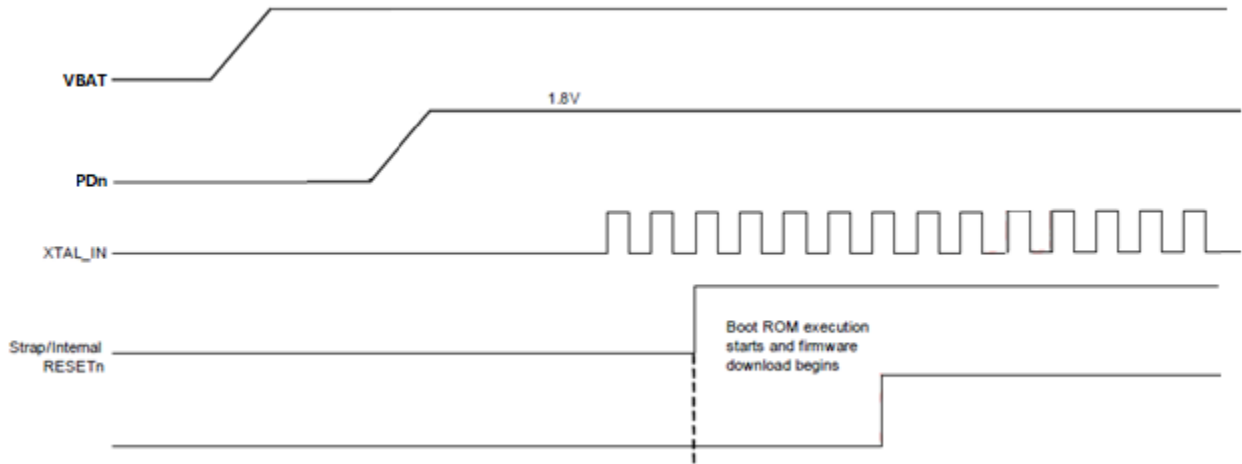
3.3 Digital IO Pin DC Characteristics

Symbol	Parameter	Minimum	Typical	Maximum	Unit
V _{IH}	Input high voltage	1.26	-	2.2	V
V _{IL}	Input low voltage	-0.4	-	0.54	V
V _{OH}	Output High Voltage	1.4	-	-	V
V _{OL}	Output Low Voltage	-	-	0.4	V

3.4 Power up Timing Sequence

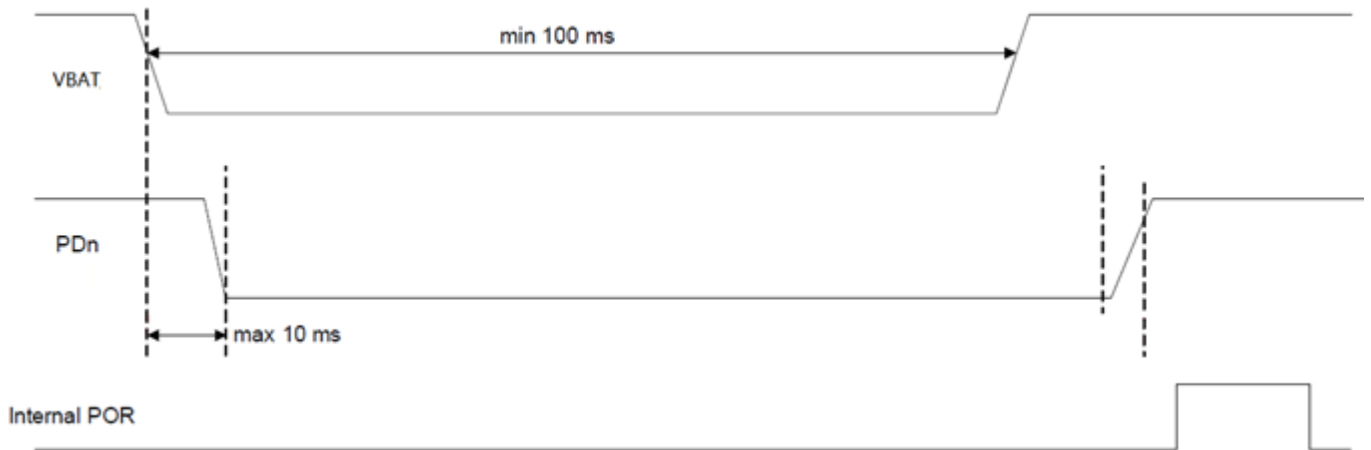
Power-up Sequence

VDDIO/PdN no specific time requirement, just need to follow up the power on sequence waveform.



Power-down Sequence

The table is AW-CM358MA module power down sequence, the maximum ramp-down time for PDn from VBAT assertion is 10ms. VBAT must be asserted a minimum of 100 ms to guarantee that PDn are discharged to less than 0.2V for the POR generate properly after VBAT is deasserted.



3.4.1 SDIO Host Interface Specification

The AW-CM358MA supports a SDIO device interface that conforms to the industry SDIO Full-Speed card specification and allows a host controller using the SDIO bus protocol to access the Wireless SoC device.

The AW-CM358MA acts as the device on the SDIO bus. The host unit can access registers of the SDIO interface directly and can access shared memory in the device through the use of BARs and a DMA engine.

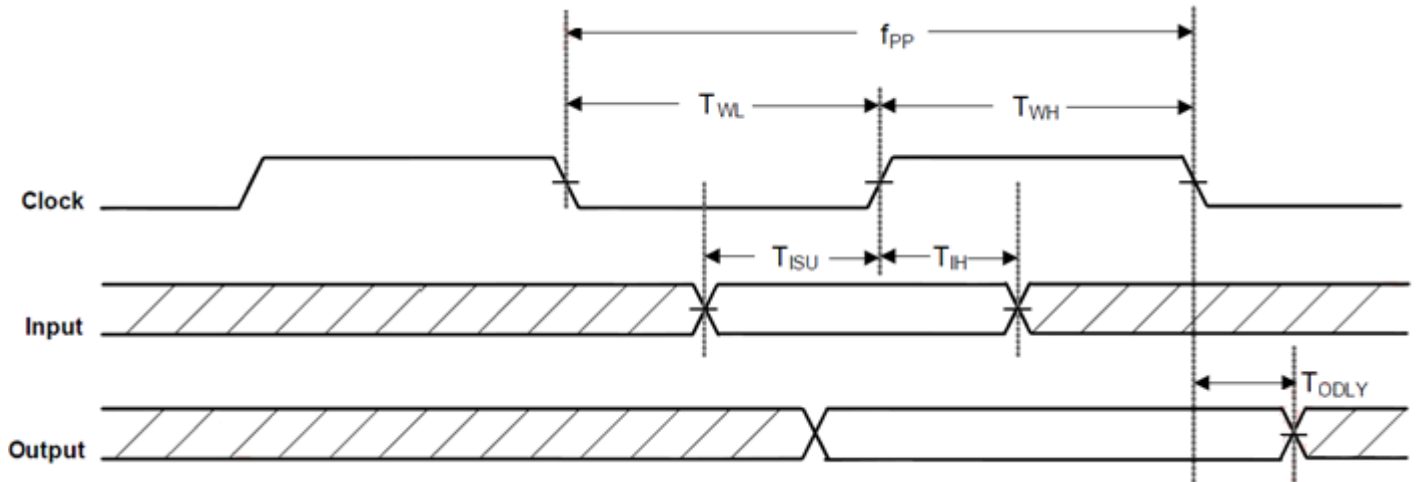
- ◆ Support SDIO 3.0 Standard.
- ◆ On-chip memory used for CIS.
- ◆ Supports 4-bit SDIO and 1-bit SDIO transfer modes.
- ◆ Special interrupt register for information exchange.

SDIO Interface Signals

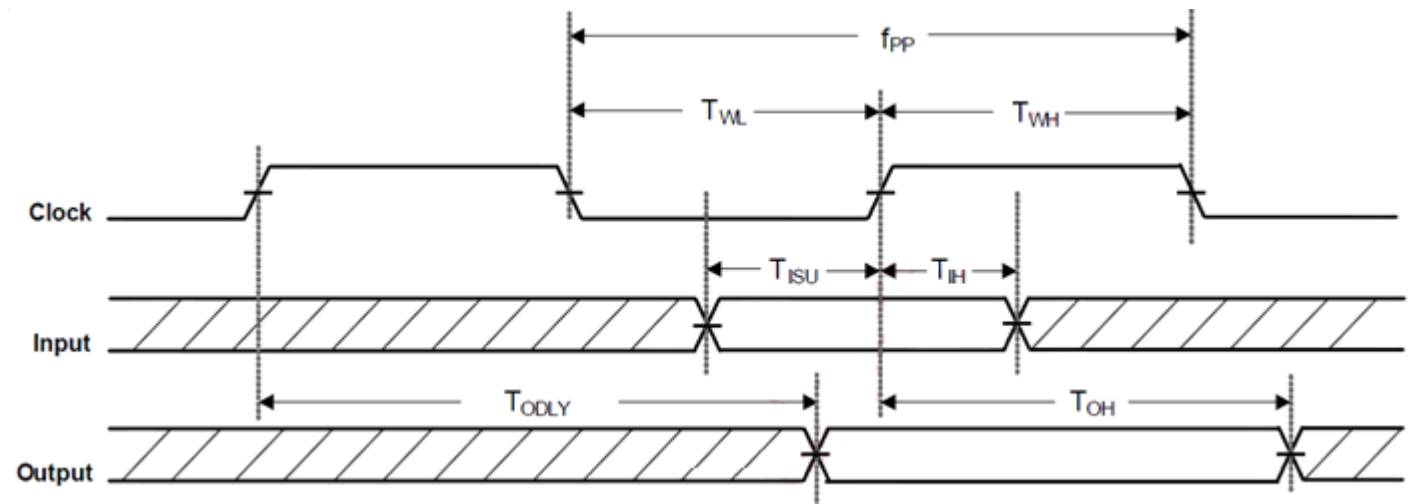
AW-CM358MA SDIO Pin Name	Type	Description
SDIO_DATA_CLK	I	SDIO 4-bit mode: Clock SDIO 1-bit mode: Clock
SDIO_DATA_CMD	I/O	SDIO 4-bit mode: Command line SDIO 1-bit mode: Command line
SDIO_DATA_3	I/O	SDIO 4-bit mode: Data line Bit[3] SDIO 1-bit mode: Not used
SDIO_DATA_2	I/O	SDIO 4-bit mode: Data line Bit[2] or Read Wait (optional) SDIO 1-bit mode: Read Wait (optional)
SDIO_DATA_1	I/O	SDIO 4-bit mode: Data line Bit[1] SDIO 1-bit mode: Interrupt
SDIO_DATA_0	I/O	SDIO 4-bit mode: Data line Bit[0] SDIO 1-bit mode: Data line

Default Speed, High-Speed Modes

SDIO Protocol Timing Diagram – Default Speed Mode (3.3V)



SDIO Protocol Timing Diagram – High Speed Mode (3.3V)



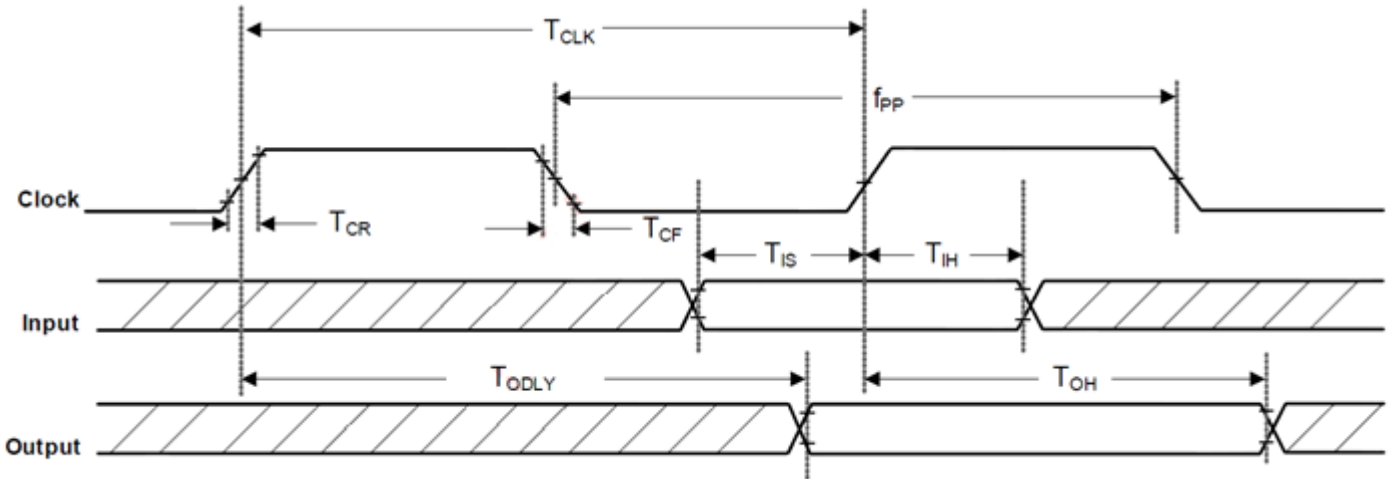
SDIO Timing Data- Default Speed, High-Speed Modes (3.3V)

Symbol	Parameter	Condition	Min	Max	Units
f_{pp}	CLK Frequency	Normal	0	25	MHz
		High Speed	0	50	
t_{WL}	CLK low Time	Normal	10	-	ns
		High Speed	7	-	
t_{WH}	CLK High Time	Normal	10	-	
		High Speed	7	-	

t_{ISU}	Input Setup Time	Normal	5	-
		High Speed	6	-
t_{IH}	Input Hold Time	Normal	5	-
		High Speed	2	-
t_{ODLY}	Output Delay Time	Normal	-	14
		High Speed	-	14
T_{OH}	Output hold time	High Speed	2.5	

1. For SDIO 2.0 running at 50MHz clock frequency, only 1.8V is supported.
2. For SDIO 2.0 running at 25MHz clock frequency, 1.8V or 3.3V is supported.

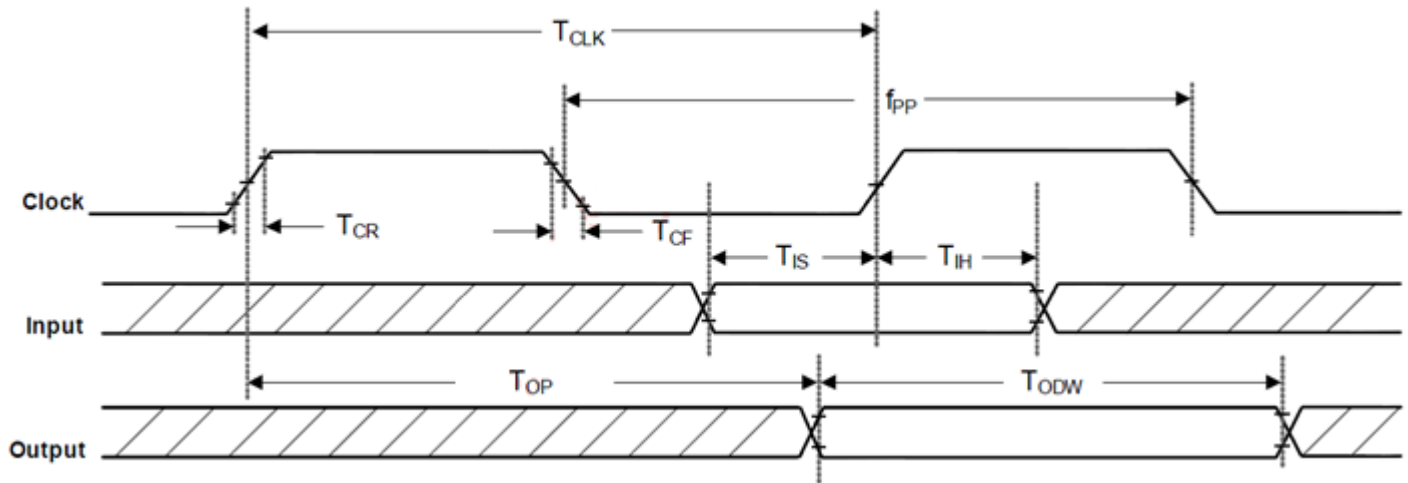
SDIO Protocol Timing Diagram – SDR12, SDR25, SDR50 Modes (up to 100MHz) (1.8V)



SDIO Timing Data- SDR12, SDR25, SDR50 Modes (up to 100MHz) (1.8V)

Symbol	Parameter	Condition	Min	Typ	Max	Units
f_{pp}	CLK Frequency	SDR12/25/50	25	-	100	MHz
T_{IS}	Input setup time	SDR12/25/50	3	-	-	ns
T_{IH}	Input hold time	SDR12/25/50	0.8	-	-	ns
T_{CLK}	Clock time	SDR12/25/50	10	-	40	ns
T_{CR}, T_{CF}	Rise time, fall time	SDR12/25/50	-	-	0.2*T _{CLK}	ns
T_{ODLY}	Output delay time	SDR12/25/50	-	-	7.5	ns
T_{OH}	Output hold time	SDR12/25/50	1.5	-	-	ns

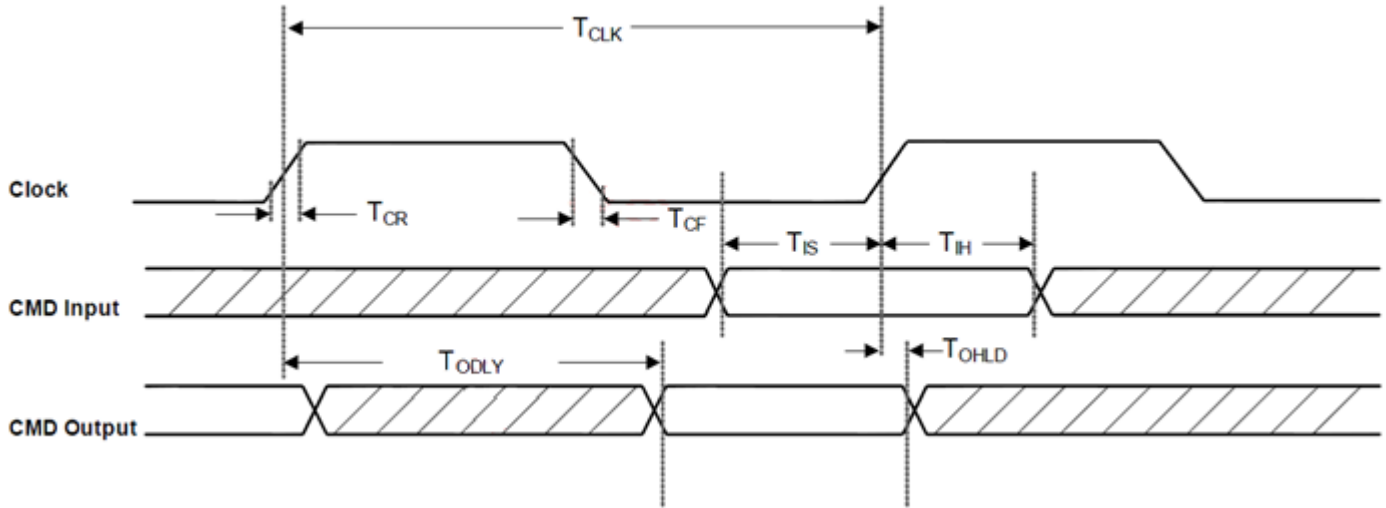
SDIO Protocol Timing Diagram – SDR104 Mode (208MHz)



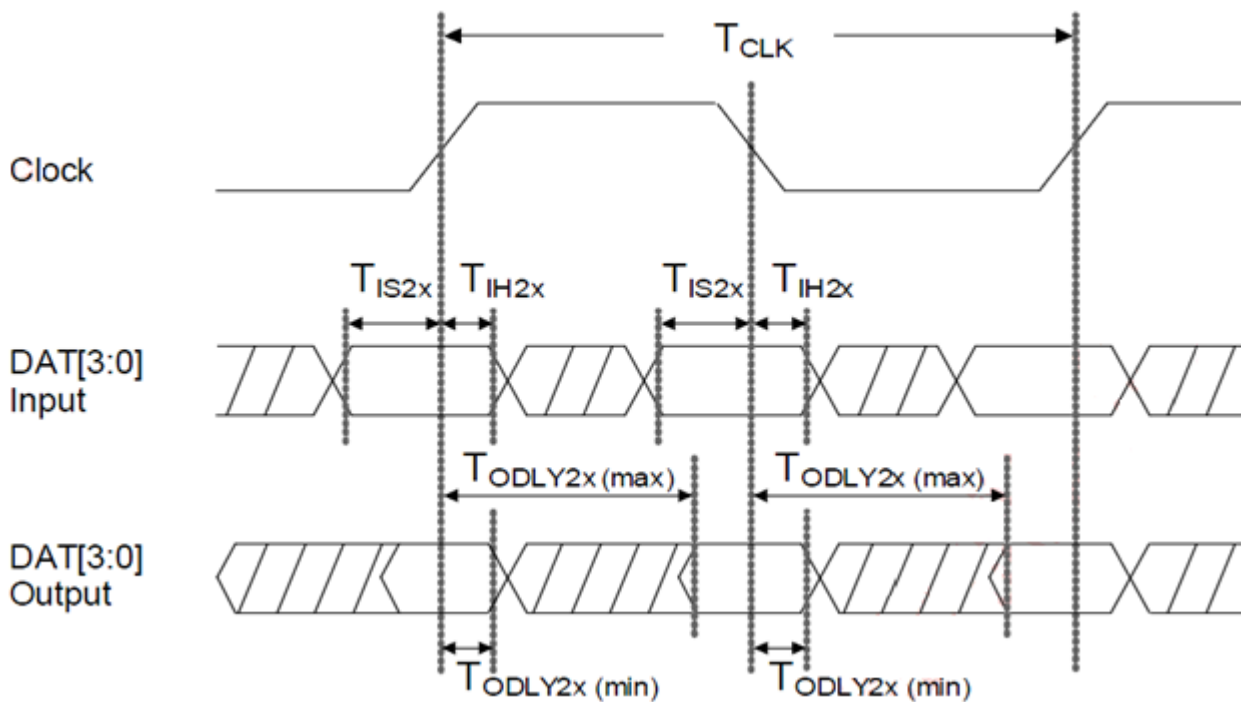
SDIO Timing Data- SDR104 Mode (208MHz)

Symbol	Parameter	Condition	Min	Typ	Max	Units
f_{pp}	CLK Frequency	SDR104	0	-	208	MHz
T_{IS}	Input setup time	SDR104	1.4	-	-	ns
T_{IH}	Input hold time	SDR104	0.8	-	-	ns
T_{CLK}	Clock time	SDR104	4.8	-	-	ns
T_{CR}, T_{CF}	Rise time, fall time	SDR104	-	-	$0.2 \cdot T_{CLK}$	ns
T_{ODLY}	Output delay time	SDR104	0	-	10	ns
T_{OH}	Output hold time	SDR104	2.88	-	-	ns

SDIO CMD Timing Diagram – DDR50 Mode (50MHz)



SDIO SAT [3:0] Timing Diagram – SDR50 Mode (50MHz)



SDIO Timing Data- DDR50 Mode (50MHz)

Symbol	Parameter	Condition	Min	Typ	Max	Units
Clock						
T_{CLK}	Clock time	DDR50	20	-	-	ns
T_{CR}, T_{CF}	Rise time, fall time	DDR50	-	-	$0.2 \cdot T_{CLK}$	Ns

Clock Duty		DDR50	45	-	55	%
CMD Input						
T_{IS}	Input setup time	DDR50	6	-	-	ns
T_{IH}	Input hold time	DDR50	0.8	-	-	ns
CMD Output						
T_{ODLY}	Output delay time during data transfer mode	DDR50	-	-	13.7	ns
T_{OHL D}	Output hold time	DDR50	1.5	-	-	ns
DAT [3:0] Input						
T_{IS2X}	Input hold time	DDR50	3	-	-	ns
T_{IH2X}	Input hold time	DDR50	0.8	-	-	ns
DAT [3:0] Output						
T_{ODLY2X(max)}	Output delay time during data transfer mode	DDR50	-	-	7	ns
T_{ODLY2X(min)}	Output hold time	DDR50	1.5	-	-	ns

3.4.2 UART Interface

High-Speed UART interface

The AW-CM358MA supports a high-speed Universal Asynchronous Receiver/ Transmitter (UART) interface, compliant to the industry standard 16550 specification.

- ◆ FIFO mode permanently selected for transmit and receive operations.
- ◆ 2 pins for transmit and receive operations.
- ◆ 2 flow control pins.
- ◆ Interrupt triggers for low-power, internal CPU (for debug purposes).
- ◆ Support diagnostic tests.
- ◆ Support data input/ output operations for peripheral devices connected through a standard UART interface.

UART Interface Signals

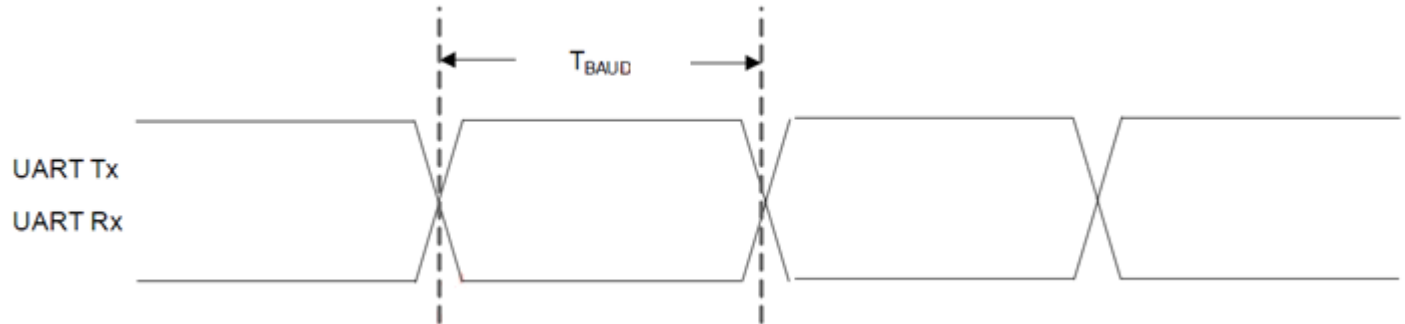
Pin Number	Signal Name	16550 Standard Name	Type	Description
22	UART_SOUT	SOUT	O	Serial data
32	UART_SIN	SIN	I	Serial data
36	UART_CTSn	CTS _n	I	Clear To Send
34	UART_RTSn	RTS _n	O	Request To Send

UART Baud Rates Supported

Baud Rate				
1200	38400	460800	1500000	3000000
2400	57600	500000	1843200	3250000
4800	76800	921600	2000000	3692300
9600	115200	1000000	2100000	4000000
19200	230400	1382400	2764800	-

The UART Tx and Rx pins are powered from the VDDIO voltage supply.

UART Timing Diagram



UART Timing Data

Symbol	Parameter	Condition	Min	Typ	Max	Units
TBAUD	Baud rate	38.4MHz input clock	250	-	-	ns

3.4.3 Frequency Reference

An external crystal is used for generating all radio frequencies and normal operation clocking. As an alternative, an external frequency reference driven by a temperature-compensated crystal oscillator (TCXO) signal may be used. No software settings are required to differentiate between the two. In addition, a low-power oscillator (LPO) is provided for lower power mode timing.

External 32.768KHz Low-Power Oscillator

Symbol	Parameter	Min	Typ	Max	Units
CLK	Clock frequency range/ accuracy CMOS input clock signal type ± 250 ppm (initial, aging, temperature)	-	32.768	-	kHz
V_{IH}	Input levels, where VDDIO=1.8, 3.3V for V _{IH} , V _{IL}	0.7*VDDIO	-	VDDIO_0.4	V
V_{IL}		-0.4	-	0.3*VDDIO	V
PN	Phase noise requirement (@ 100KHz)	-	-125	-	dBc/Hz
J_c	Cycle jitter	-	1.5	-	ns (RMS)
SR	Slew rate limit (10-90%)	-	-	100	ns
DC	Duty cycle tolerance	20	-	80	%

The AW-CM358MA module crystal specifications

3.5 Power Consumption*

3.5.1 WLAN

No.	Item			VBAT_IN=3.3 V		
				Max.	Avg.	
1	Power Down ^{*(1)(2)}			1.4mA	1.4mA	
2	Sleep ^{*(2)(4)} (Not associated with AP)			1.5mA	1.42mA	
3	Power Save (2.4GHz) ^{*(2)(3)(4)}			50mA	3.05mA	
4	Power Save (5GHz) ^{*(2)(3)(4)}			84mA	2.47mA	
Band (GHz)	Mode	BW (MHz)	RF Power (dBm)	Transmit		
				Max.	Avg.	Duty(%) (Mean)
2.4	11b@1Mbps	20	16	373	369	99
	11g@54Mbps	20	14	286	283	78
	11n@MCS7	40	12	239	235	76
5	11a@6Mbps	20	13	289	294	75
	11n@MCS7	40	10	227	224	74
	11ac@MCS0	20	10	247	244	97
	11ac@MCS9 NSS1	80	8	211	209	51
Band (GHz)	Mode	BW(MHz)	Receive			
			Max.	Avg.		
2.4	11b@1Mbps	20	60	57		
	11n@MCS7	40	67	65		
5	11a@6Mbps	20	79	71		
	11ac@MCS9 NSS1	80	105	99		

* The power consumption is based on Azurewave test environment, these data for reference only.

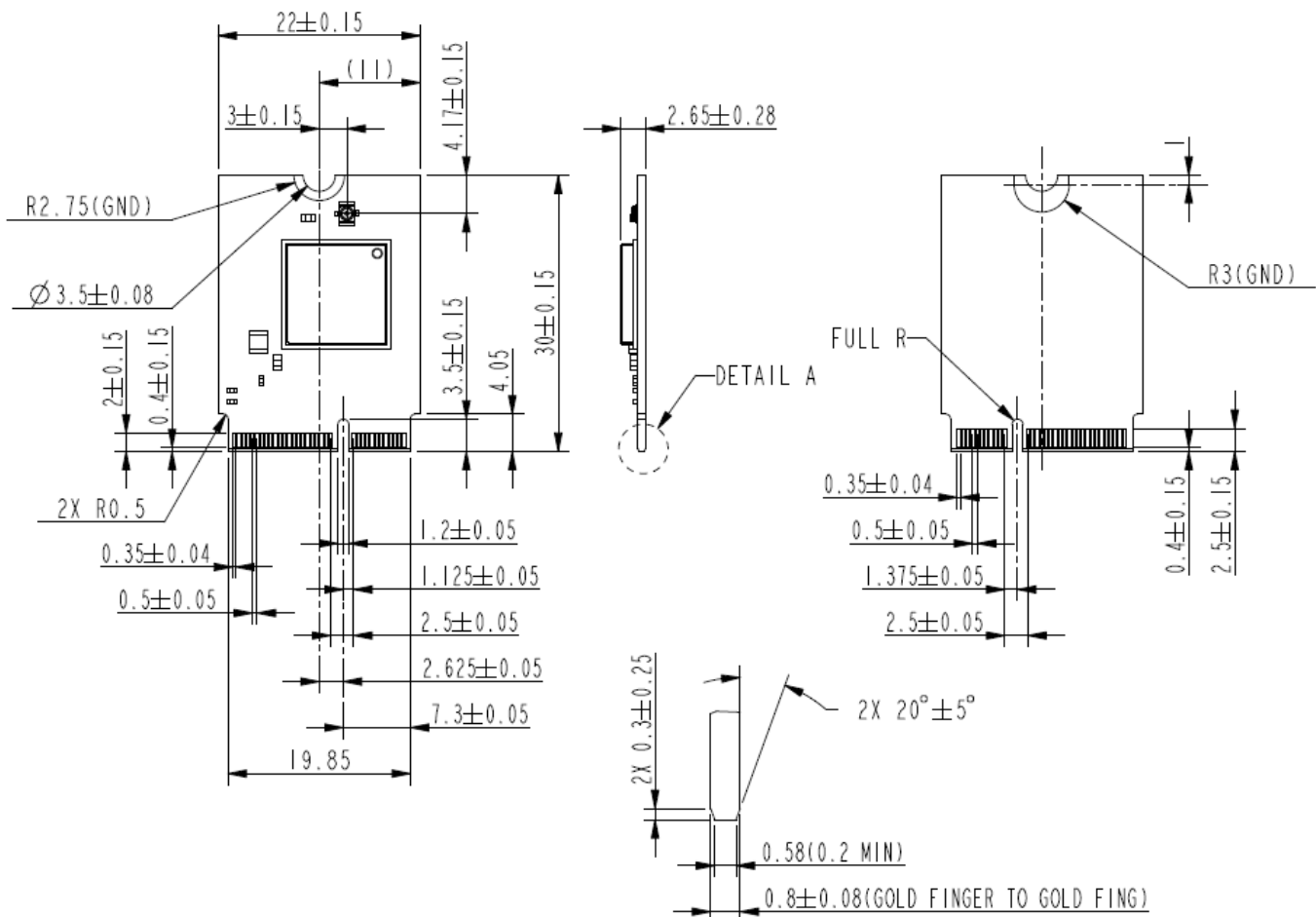
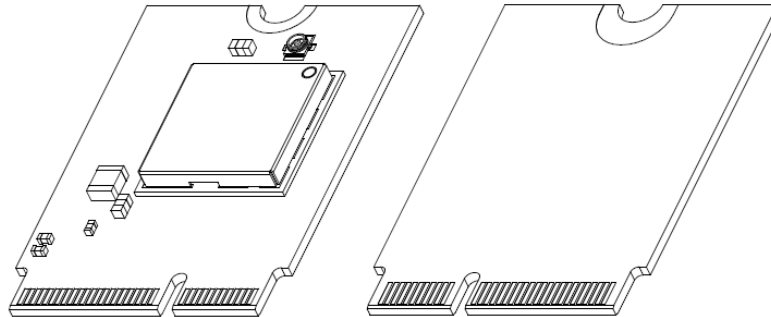
3.5.2 Bluetooth

No.	Mode	Packet Type	RF Power (dBm)	VBAT_IN=3.3 V	
				Max.	Avg.
1	Transmit ^{*(2)}	DH5	4	78	69
2	Receive ^{*(2)}	3-DH5	n/a	81	67

* The power consumption is based on Azurewave test environment, these data for reference only.

4. Mechanical Information

4.1 Mechanical Drawing



DETAIL: A
SCALE: 4.000

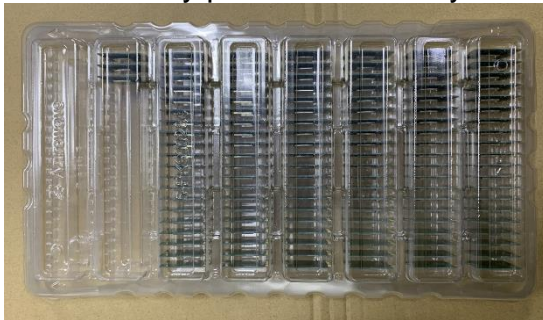
TOLERANCE UNLESS OTHERWISE SPECIFIED: $\pm 0.1 \text{ mm}$

5. Packaging Information

1. 160pcs AW-CM358MA modules put in the one bottom tray



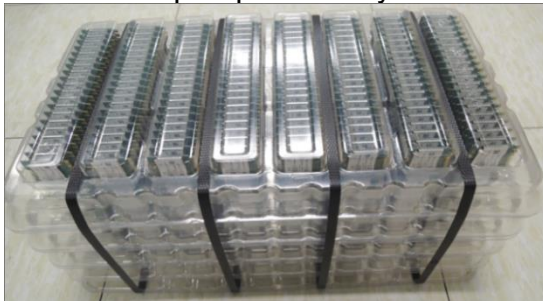
2. One cover tray put on bottom tray



3. **5pcs tray** (cover + bottom) stacked together



4. Use P.P Strap to pack 5 trays



Note : 1 Tray = 160pcs cards, 5 Trays = 1 Box = 800 pcs, Carton = 2 Boxes = 1,600 pcs

5. Put packed trays into inner box



6. Seal the inner box by AzureWave tape



7. One package label pasted in side of inner box



Example:

8. Two inner boxes put into one carton; If only one inner box has modules, "Empty" label pasted on the other one inner box










Example:

9. Seal the carton by AzureWave tape



10. One carton label and box label pasted on the carton. If the carton is not full, one balance label pasted on the carton



<p>Example of carton label</p>	<table border="1"> <tr> <td colspan="2" style="text-align: center;">  </td> </tr> <tr> <td>AzureWave P/N</td> <td></td> </tr> <tr> <td>Customer</td> <td>由業務提供</td> </tr> <tr> <td>Customer P/N</td> <td>由業務提供</td> </tr> <tr> <td>Customer PO</td> <td>由業務提供</td> </tr> <tr> <td>Description</td> <td>AW-XXXXXX</td> </tr> <tr> <td>QTY</td> <td>pcs</td> </tr> <tr> <td>C/N</td> <td></td> </tr> <tr> <td>N.W.</td> <td>G.W.</td> </tr> <tr> <td colspan="2" style="text-align: center;">  </td> </tr> </table>			AzureWave P/N		Customer	由業務提供	Customer P/N	由業務提供	Customer PO	由業務提供	Description	AW-XXXXXX	QTY	pcs	C/N		N.W.	G.W.		
																					
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<p>Example of box label</p>																					
<p>Example of balance label</p>	